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## Film Stress of Ti film prepared by PVD75 e-beam evaporator

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### Keywords

Film Stress, Ti film, PVD75 e-beam evaporator

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# **Film Stress of Ti film prepared by PVD75 e-beam evaporator (Graduate Student Fellow Program)**

Prepared by Zisong Nie (11/17/2014)

- Deposition rate = 5 Å/s
- Tooling factor = 33%

Result:

- Film thickness = 245.6 nm (P7 2D stylus profiler)
- Average stress = 221.5 MPa (Tensile) (P7 2D&3D stylus profiler)